

LATIOHM 82-02 PD09

Semiconductive/dissipative product based on Polyamide 12 (PA12).
Unfilled.

PHYSICAL PROPERTIES	STANDARD	VALUE MEASURE UNITS
Density	ISO 1183	1.22 g/cm ³
Linear shrinkage at moulding		
Longitudinal (0.078in/8,700psi)	ISO 294-4	0.009 ÷ 0.011 in/in
Transversal (0.078in/8,700psi)	ISO 294-4	0.009 ÷ 0.011 in/in
MECHANICAL PROPERTIES	STANDARD	VALUE MEASURE UNITS
CHARPY impact strength		
Unnotched, at +73°F	ISO 179-1eU	11.68 ft.lb/in ²
Notched, at +73°F	ISO 179-1eA	1.17 ft.lb/in ²
Tensile elongation		
At yield (0.196 in/min), 73°F	ISO 527 (1)	15.0 %
At break (0.196 in/min), 73°F	ISO 527 (1)	50.0 %
Tensile strength		
At yield (0.196 in/min), 73°F	ISO 527 (1)	7200 psi
At break (0.196 in/min), 73°F	ISO 527 (1)	6500 psi
Elastic modulus		
Tensile (speed 0.04 in/min), at 73°F	ISO 527 (1)	300 kpsi

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THERMAL PROPERTIES	STANDARD	VALUE MEASURE UNITS
VICAT - Softening point		
11 lb (heating rate 122°F/h)	ISO 306	284 °F
HDT - Heat Deflection Temperature		
66 psi	ISO 75	239 °F
264 psi	ISO 75	122 °F
ELECTRICAL PROPERTIES	STANDARD	VALUE MEASURE UNITS
Electrical resistivity		
Surface	ASTM D 257	1E2 ohm

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MATERIAL - STORAGE

Sealed, undamaged packages has to be kept in dry storage facilities, providing they are also able to protect them from weather and accidental damages.

HANDLING AND SAFETY

Detailed information about a safe treatment of the material are indicated in the "Material Safety Data Sheet" (MSDS) furnished with the first material supply. The MSDS may be also sent again in case of loss.

PREDRYING CONDITIONS

At least 3 hours at $176 \div 212^{\circ}\text{F}$

These are the suggested conditions to reduce the moisture content to adequate levels. Temperature and drying time can be reduced by using vacuum ovens

ACTUAL MELT TEMPERATURE

$410 \div 464^{\circ}\text{F}$

The injection molding machine settings needed to obtain the suggested melt temperature will depend greatly on shot size and machine capacity, as well as other molding parameters such as: injection speed, screw RPM, back pressure, etc. On small machines, running short cycles, it is possible to use higher melt temperatures to improve plastification, fluidity and surface appearance, paying attention to any indication of material degradation.

MOLD TEMPERATURE

$113 \div 140^{\circ}\text{F}$

The mold temperature suggested above is the actual tool steel temperature. This can be significantly different from the tool settings, due to the cooling system efficiency and the accuracy of the temperature control on the tool.

INJECTION SPEED

Medium

The advisable injection speed greatly depends on cavity geometry and injection molding machine size. The use of high injection speed can improve the surface appearance, but it can also cause outgassing and burn marks due to overheating through shear stress.

REGRIND USAGE

The use of regrind is possible, but should be assessed on the basis of the project, moulding parameters, and type of grinding used. The effect of using regrind on material properties must be evaluated by the customer on its specific project and process. High percentages of regrind may cause a reduction in viscosity, reducing mechanical properties, first resilience.

HOT RUNNER MOLDS

Hot runner moulds may be used when a very tight temperature control is assured.

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TO AVOID

In order to prevent any material degradation, over-dimensioned machines should be avoided.

NOTES

The products mentioned herein are not suitable for applications in contact with foodstuff or for potable water transportation, or for toy manufacturing. The products mentioned herein are not suitable for applications in the pharmaceutical, medical or dental sector.